

## METALLIZATION EQUIPMENT



**MODEL:** DENTON DV-602

**INSTALLATION PLACE:** Cleanroom of “Nanotechnology and Microsystems Laboratory”, Department of Microelectronics

**DESCRIPTION:**

E-gun evaporation system for metal deposition with 6 positions for 75 or 100mm wafers and a special position for small samples

### SPECIFICATIONS

1. Resistance Evaporation Source (2kVA source): capable of 400A(at 5V) or 200A(at 10V)
2. Deposition rate: 10 – 70 Å/min
3. Semiconductors, oxides, resist etc.
4. Sample size: 3” / 4” wafer and small pieces
5. Vacuum System:  $P_{\text{chamber}} = 2 \times 10^{-6}$ Torr.
  - a. Cryogenic pump (‘CRYO-TORR 8’-CTI CRYOGENICS,HELIX TECHNOLOGY CORPORATION) for metal deposition  $P_{\text{depos}} \sim 10^{-5}$ Torr,
  - b. Mechanical oil pump (Leybold D65 BCS) for pressure up to  $P = 0.5 \times 10^{-2}$ Torr
6. Metal target: Pellets

### APPLICATIONS

Metal thin films deposited for contacts, electrodes, interconnect lines etc

### CERTIFICATION/ACCREDITATION

The facility is not certified or accredited

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